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Nota di contenuto	BOGATIN'S PRACTICAL GUIDE to PROTOTYPE BREADBOARD and PCB DESIGN -- Table of Contents -- Chapter 1 A Getting-Started Guide -- 1.1 Who This Book Is For -- 1.2 Getting Stuff Done -- 1.3 Cost-Performance Trade-offs -- 1.4 Errors, Best Practices, and Habits -- 1.5 Learn to Design-in Success -- 1.6 A Getting-Started Guide for Signal Integrity -- 1.7 The Seven-Step Process -- 1.8 Risk Management and Mitigation -- 1.9 Two Risk Management Design Strategies -- 1.0 Master of Murphy's Law -- 1.11 Proof of Concept -- 1.12 Practice Questions -- Chapter 2 PCB Technology -- 2.1 PCB, PWB, or PCA? -- 2.2 Physical Design of a PCB -- 2.3 Vias Technologies -- 2.4 Thermal and Thermal Relief Vias -- 2.5 Other Layers -- 2.6 The Soldermask Layer -- 2.7 Surface Finishes -- 2.8 The Silk Screen -- 2.9 What the Fab Vendor Needs -- 2.10 Practice Questions -- Chapter 3 Signal Integrity and Interconnects -- 3.1 Transparent Interconnects -- 3.2 When Interconnects are NOT Transparent -- 3.3 Where Signal Integrity Lives -- 3.4 Six Categories of Electrical Noise -- 3.5 Families of SI/PI/EMI Problems -- 3.6 In Principle and In Practice -- 3.7 Net Classes and Interconnect Problems -- 3.9 Design for X -- 3.10 Practice Questions -- Chapter 4 Electrical Properties of Interconnects -- 4.1 Ideal vs Real Circuit Elements -- 4.2 Equivalent Electrical Circuit Models -- 4.3 Parasitic Extraction of R, L, and C Elements -- 4.4 Describing Cross Talk -- 4.5 Estimating Mutual Inductance -- 4.6 Training Your Engineer's Mind's Eye -- 4.7 Electrically Long Interconnects -- 4.8 Electrically Short and Electrically Long -- 4.9 Practice Questions --

Chapter 5 Trace Width Considerations: Max Current -- 5.1 Best design practices -- 5.2 Minimum Fabrication Trace Width -- 5.3 Copper Thickness as Ounces of Copper -- 5.4 Maximum Current Handling of a Trace -- 5.5 Maximum Current Through a Via. 5.6 Thermal Runaway with Constant Current -- 5.7 Practice Questions -- Chapter 6 Trace Width Considerations: Series Resistance -- 6.1 Resistance of Any Uniform Conductor -- 6.2 Sheet Resistance of a Copper Layer -- 6.3 Measuring Very Low Resistances -- 6.4 Voltage Drop Across Traces -- 6.5 The Thevenin Model of a Voltage Source -- 6.6 How Much Trace Resistance Is too Much? -- 6.7 The Resistance of a Via -- 6.8 Resistance of a Thermal Relief Via -- 6.9 Practice Questions -- Chapter 7 The Seven Steps in Creating a PCB -- 7.1 Step 1: Plan of Record -- 7.2 Step 2: Create the BOM -- 7.3 Step 3: Complete the Schematic -- 7.4 Step 4: Complete the Layout, Order the Parts -- 7.5 Steps 5 and 6: Assembly and Bring-Up -- 7.6 Step 7: Documentation -- 7.7 Practice Questions -- Chapter 8 Step 1, POR: Risk Mitigation -- 8.1 Visualize the Entire Project Before You Begin -- 8.2 Avoid Feature Creep -- 8.3 Estimate Everything You Can -- 8.4 Preliminary BOM: Critical Components -- 8.5 Risk Assessment -- 8.6 Risk Mitigation: Tented Vias -- 8.7 Risk Mitigation: Qualified Parts -- 8.8 Practice Questions -- Chapter 9 Risk Reduction: Datasheets, Reverse Engineering, and Component Selection -- 9.1 Take Responsibility for Your Design -- 9.2 Reducing the Risk of a Design Problem -- 9.3 Understand Your Circuit -- 9.4 Read Datasheets Critically -- 9.5 Build Simple Evaluation Prototypes -- 9.6 Reverse Engineer Components -- 9.7 Reuse Parts -- 9.8 Practice Questions -- Chapter 10 Risk Reduction: Virtual and Real Prototypes -- 10.1 Getting Started with Circuit Simulation -- 10.2 Practice Safe Simulation -- 10.3 Simulating a 555 Circuit -- 10.4 Purchase an Evaluation Board -- 10.5 Real Prototypes with Modules -- 10.6 Practice Questions -- Chapter 11 Risk Reduction: Prototyping with a Solderless Breadboard -- 11.1 Build a Real Prototype -- 11.2 Solderless Breadboards for POC. 11.3 Features of a Solderless Breadboard -- 11.4 Bandwidth Limitations -- 11.5 A Simple Breakout Board -- 11.6 The Mini Solderless Breadboard -- 11.7 Best Wiring Habits -- 11.8 Habit #1: Consistent Column Assignments -- 11.9 Habit #2: Color Code the Wires -- 11.10 Habit #3: Keep Signal Traces Short -- 11.11 Habit #4: Avoid a Shared Return Path -- 11.12 Habit #5: Route Signal-Return Pairs -- 11.13 Habit #6: Keep Component Leads Short -- 11.14 Practice Questions -- Chapter 12 Switching Noise and Return Path Routing -- 12.1 The Origin of Switching Noise -- 12.2 Signal-Return Path Loops -- 12.3 Where Does Return Current Flow? -- 12.4 A Plane as a Return Path -- 12.5 Ground -- 12.6 Avoid Gaps in the Return Plane -- 12.7 Summary of the Best design practices -- 12.8 Practice Questions -- Chapter 13 Power Delivery -- 13.1 Origin of Power Rail Switching Noise -- 13.2 Calculating Loop Inductance -- 13.3 Measuring PDN Switching Noise -- 13.4 The Role of Decoupling Capacitors -- 13.5 Where Do Decoupling Capacitors Go? -- 13.6 The Power Delivery Path -- 13.7 Inrush Current -- 13.8 Summary of the Eight Habits for Using a SSB -- 13.9 Practice Questions -- Chapter 14 Design for Performance: The PDN on a PCB -- 14.1 VRM specifications -- 14.2 Voltage Regulator Module -- 14.3 Self- and Mutual-Aggression Noise -- 14.4 Power and Ground Loop Inductance -- 14.5 Decoupling Capacitors -- 14.6 A Decoupling Capacitor Myth -- Part 1 -- 14.7 A Decoupling Capacitor Myth -- Part 2 -- 14.8 Routing for Power Distribution -- 14.9 Ferrite Beads -- 14.10 Summary of the Best design practices -- 14.11 Practice Questions -- Chapter 15 Risk Reduction: Design for Bring-Up -- 15.1 Test is Too General a Term -- 15.2 What Does It Mean to "Work"? -- 15.3 Design

for Bring-Up -- 15.4 Add Design for Bring-Up Features -- 15.5 Jumper Switches -- 15.6 LED indicators -- 15.7 Test Points.
15.8 The Power Rail as a Diagnostic -- 15.9 Practice Questions --
Chapter 16 Risk Reduction: Design Reviews -- 16.1 The Preliminary Design Review -- 16.2 The Critical Design Review -- 16.3 DRC for DFM in the CDR -- 16.4 DRC for Signal Integrity -- 16.5 Layout Review -- 16.6 Practice Questions -- Chapter 17 Step 2: Surface-Mount or Through-Hole Parts -- 17.1 Through-Hole and Surface-Mount -- 17.2 Types of SMT Parts -- 17.3 Integrated Circuit Components -- 17.4 Practice Questions -- Chapter 18 Finding the One Part in a Million -- 18.1 An Important Selection Process -- 18.2 Trade-offs in Selecting Parts -- 18.3 The Search Order to Select a Part -- 18.4 Selecting Resistors -- 18.5 Selecting Capacitors -- 18.6 The BOM -- 18.7 Summary of the Best Design Practices -- 18.8 Selecting Parts for Automated Assembly -- 18.9 Practice Questions -- Chapter 19 Step 3: Schematic Capture and Final BOM -- 19.1 Picking a Project Name -- 19.2 Schematic Capture -- 19.3 Take Ownership of Reference Designs -- 19.4 Add Options to Your Schematic -- 19.5 Best design practices for Schematic Entry -- 19.6 Design Review and ERC -- 19.7 Practice Questions -- Chapter 20 Step 4: Layout - Setting Up the Board -- 20.1 Layout -- 20.2 Board Dimensions -- 20.3 The Layers in a Board Stack -- 20.4 Negative and Positive Layers -- 20.5 Examples of Some Fab Shop DFM Features -- 20.6 Setting Up Design Constraints -- 20.7 Thermal Reliefs in Pads and Vias -- 20.8 Set Up Board Size and Keepout Layer -- 20.9 Practice Questions -- Chapter 21 Floor Planning and Routing Priority -- 21.1 Part Placement -- 21.2 The Order of Placement and Routing -- 21.3 First Priority: Ground Plane on the Bottom Layer -- 21.4 Second Priority: Decoupling Capacitors -- 21.5 Third Priority: Ground Connections -- 21.6 Fourth Priority: Digital Signals, Congested Signals -- 21.7 Fifth Priority: Power Paths.
21.8 The Silk Screen -- 21.9 Check the Soldermask -- 21.10 Soldermask Color -- 21.11 Layout - Critical Design Review -- 21.12 Practice Questions -- Chapter 22 Six Common Misconceptions about Routing -- 22.1 Myth #1: Avoid 90 Deg Corners -- 22.2 Myth #2: Add Copper Pour on Signal Layers -- 22.3 Myth #3: Use Different Value Decoupling Capacitors -- 22.4 Myth #4: Split Ground Plan -- 22.5 Myth #5: Use Power Planes -- 22.6 Myth #6: Use 50 Ohm Impedance Traces -- 22.7 Practice Questions -- Chapter 23 Four-Layer Boards -- 23.1 Two-Layer Stack-Ups -- 23.2 A 4-Layer Board -- 23.3 Four-Layer Stack-Up Options -- 23.4 Stack-Up Options with Two Planes -- 23.5 The Recommended 4-Layer Stack-Up -- 23.6 When Signals Change Return Planes -- 23.7 Practice Questions -- Chapter 24 Release the Board to the Fab Shop -- 24.1 Gerber Files -- 24.2 Cost Adders -- 24.3 Board Release Checklist -- 24.4 Practice Questions -- Chapter 25 Step 6: Bring-Up -- 25.1 Does Your Widget Work? -- 25.2 Prototype or Production Testing -- 25.3 Design for Bring-Up -- 25.4 Find the Root Cause -- 25.5 Problems to Expect -- 25.6 Troubleshoot Like a Detective -- 25.7 Trick #1: Recreate the Problem -- 25.8 Trick #2: Seen This Problem Before? -- 25.9 Trick #3: Round Up the Usual Suspects -- 25.10 Trick #4: Three Possible Explanations -- 25.11 A Methodology -- 25.12 Forensic Analysis -- 25.13 Coding Issues -- 25.14 Practice Questions -- Chapter 26 Step 7: Documentation -- Chapter 27 Concluding Comments -- Chapter 28 About Eric Bogatin.

Sommario/riassunto

This book focuses on the understanding of the Cylindrical Dielectric Resonator Antennas (CDRA). The book introduces the fundamentals of DRA, CDRA, identifying the modes in a CDRA, excitation techniques and recent advancements pertaining to the research of the CDRA. The latest trends in the field are discussed, including wide bandwidth of

operation, high gain, modal stability, mode and impedance matching techniques, Circularly Polarized CDAs, beam forming and MIMO applications for modern wireless systems. The experimental validation, testing, fabrication methods and machining to achieve cylindrical and its reformed shapes are also presented.
